

# AN5569

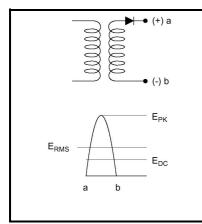
# **Standard Waveforms**

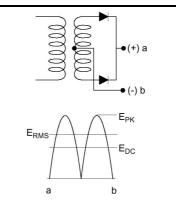
Application Note

AN5569-1.1 JULY 2005 ( LN24023)

#### SINGLE PHASE

Circuit and output voltage waveform across a - b





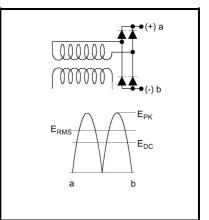


Fig. 1 : Half wave

Fig. 2 : Full wave centre tap

Fig. 3 : Full wave bridge

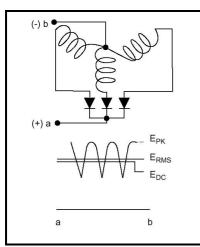
				Curr	ent Rati	ios	Voltage Ratios				
	Fundamental Ripple Frequency	I <sub>AV</sub> /I <sub>DC</sub>	I <sub>RMS</sub>	/I <sub>DC</sub> <sup>A</sup>	I <sub>РК</sub> /I <sub>DC</sub> <sup>B</sup>		I <sub>PK</sub> /I <sub>DC</sub> C		E <sub>RMS</sub> /E <sub>DC</sub> D	E <sub>RMS</sub> /E <sub>DC</sub> <sup>E</sup>	Е <sub>РК</sub> /Е <sub>DC</sub> <sup>F</sup>
			R	L	R	L	R	L			
Half Wave	1f	1.0	1.57	-	3.14	-	1.57	-	2.22	1.57	3.14
Half Wave Centre Tap	2f	0.5	0.785	0.707	1.57	1.0	0.785	0.707	1.11	2.22	1.57
Full Wave Bridge	2f	0.5	0.785	0.707	1.57	1.0	1.11	1.0	1.11	1.11	1.57

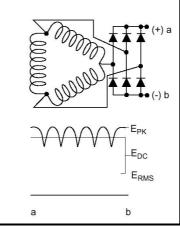
## NOTES

- R = Resistive load.
- L = Inductive load.
- A = Ratio of RMS current to DC output current. Arm fuses are rated for this RMS current.
- B = Ratio of peak device current to DC output current.
- C = Ratio of secondary RMS line current from supply to DC output current. Line fuses are rated for this RMS current.
- D = Ratio of no load RMS line to line voltage to no load DC voltage.
- E = Ratio of RMS phase voltage to DC voltage.
- F = Ratio of peak phase voltage to DC voltage.

### THREE PHASE

Circuit and output voltage waveform across a - b





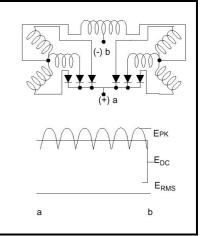


Fig. 4 : Half wave

Fig. 5 : Bridge

Fig. 6: Double star

	Fundamental Ripple Frequency		Current Ratios							Voltage Ratios		
		Ripple	I <sub>RMS</sub> /I <sub>DC</sub> <sup>A</sup>		I <sub>РК</sub> /I <sub>DC</sub> <sup>B</sup>		I <sub>РК</sub> /I <sub>DC</sub> C		E <sub>RMS</sub> /E <sub>DC</sub> D	E <sub>RMS</sub> /E <sub>DC</sub> E	E <sub>PK</sub> /E <sub>DC</sub> <sup>F</sup>	
			R	L	R	L	R	L				
Half Wave	Зf	0.33	0.588	0.577	1.21	1.0	0.588	0.577	1.48	0.855	2.1	
Bridge	6f	0.33	0.588	0.577	1.05	1.0	0.816	0.816	0.74	0.427	1.05	
Double Star	6f	0.167	0.293	0.289	0.525	0.5	0.293	0.289	1.48	0.855	2.42	

### NOTES

R = Resistive load.

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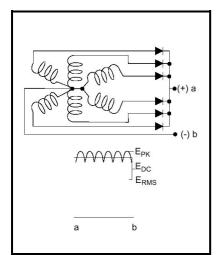
D = Ratio of no load RMS line to line voltage to no load DC voltage.

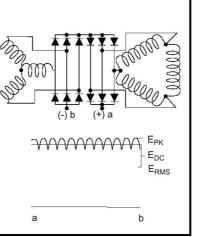
E = Ratio of RMS phase voltage to DC voltage.

F = Ratio of peak phase voltage to DC voltage.

#### SIX PHASE

Circuit and output voltage waveform across a - b





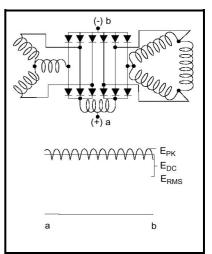


Fig. 7 : 5 Star limb core

Fig. 8 : Series bridges

Fig. 9 : Star delta with IPT

			-	Cur	Voltage Ratios						
	Fundamental Ripple Frequency	Ripple	I <sub>RMS</sub> /I <sub>DC</sub> <sup>A</sup>		I <sub>РК</sub> /I <sub>DC</sub> <sup>B</sup>		I <sub>PK</sub> /I <sub>DC</sub> C		E <sub>RMS</sub> /E <sub>DC</sub> D	E <sub>RMS</sub> /E <sub>DC</sub> <sup>E</sup>	E <sub>PK</sub> /E <sub>DC</sub> <sup>F</sup>
			R	L	R	L	R	L			
5 Star Limb Core	6f	0.167	0.408	0.408	1.05	0.5	0.408	0.408	1.48	0.74	2.1
Series Bridges	12f	0.33	0.588	0.577	1.05	1.0	0.816	0.816	0.37	-	1.05
Star Delta with IPT	12f	0.167	0.293	0.289	0.525	0.5	0.408	0.408	0.74	-	1.05

## NOTES

R = Resistive load.

L = Inductive load.

A = Ratio of RMS current to DC output current. Arm fuses are rated for this RMS current.

B = Ratio of peak device current to DC output current.

C = Ratio of secondary RMS line current from supply to DC output current. Line fuses are rated for this RMS current.

D = Ratio of no load RMS line to line voltage to no load DC voltage.

E = Ratio of RMS phase voltage to DC voltage.

F = Ratio of peak phase voltage to DC voltage.

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